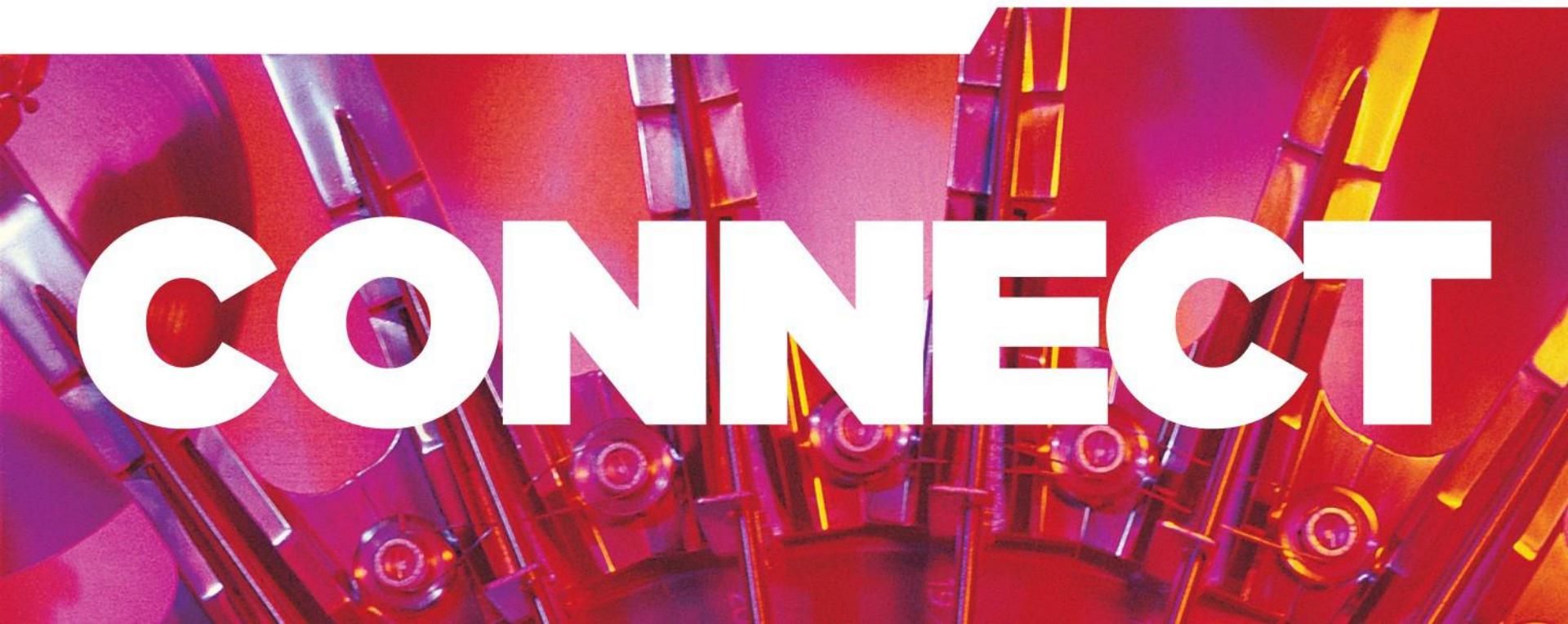


# The 10<sup>th</sup> Annual China Semiconductor Technology International Conference

March 18-19, 2019

Shanghai, China



# CONNECT



# Plenary Keynote Speakers



Dr. Simon M. Sze  
Honorary Chair Professor, NCTU



Dr. Yaoguo (Gary) Ding  
Vice President, Technology and Manufacturing Group, Intel



Dr. Min Cao  
Vice President, Path-finding, TSMC



Dr. Evangelos Elefthriou  
Fellow, Neuromorphic Computing, IBM

# CSTIC 2019 Organizers and Sponsors



Sponsors:



Organizers:



Co-organizer:



Co-sponsors:



Proceedings Publication:



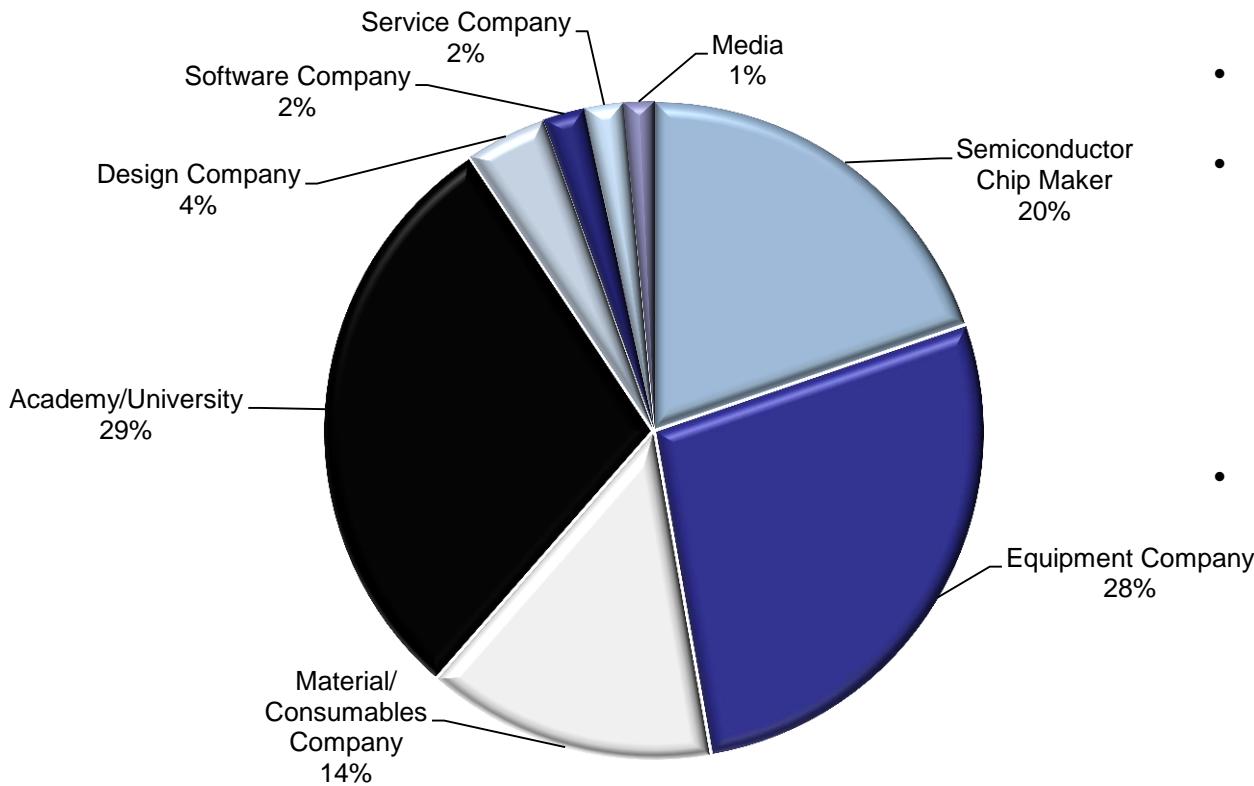
# Attendee Numbers



CSTIC Attendee Number	2019	2018
Conference	<b>830</b>	684
Plenary Session	666	549
Symposium I: Device Engineering and Memory Technology	327	287
Symposium II: Lithography and Patterning	415	318
Symposium III: Dry & Wet Etch and Cleaning	385	206
Symposium IV: Thin Film, Plating and Process Integration	264	172
Symposium V: CMP and Post-Polish Cleaning	246	178
Symposium VI: Metrology, Reliability and Testing	145	110
Symposium VII: Packaging and Assembly	212	175
Symposium VIII:MEMS, Sensors and Emerging Semiconductor Technologies	135	89
Symposium IX: Design and Automation of Circuits and Systems	149	86
Symp II & III Joint Session	214	239
Symp II, VIII & IXJoint Session	201	
Panel Discussion	214	239
WFD Short Course (Front-end)	<b>99</b>	24
WFD Short Course (Back-end)	<b>116</b>	47

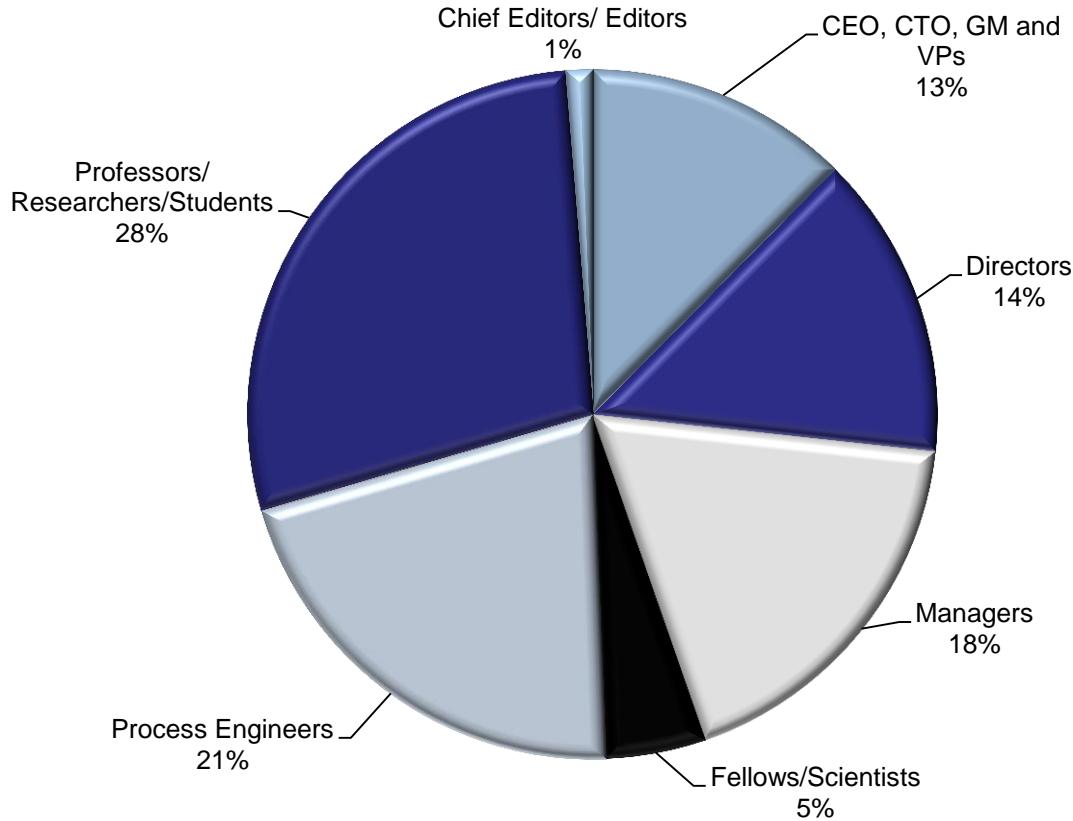
\*Symposium I-IX attendee number was Day 1 and Day 2 in total

# Attendee Industry Distribution



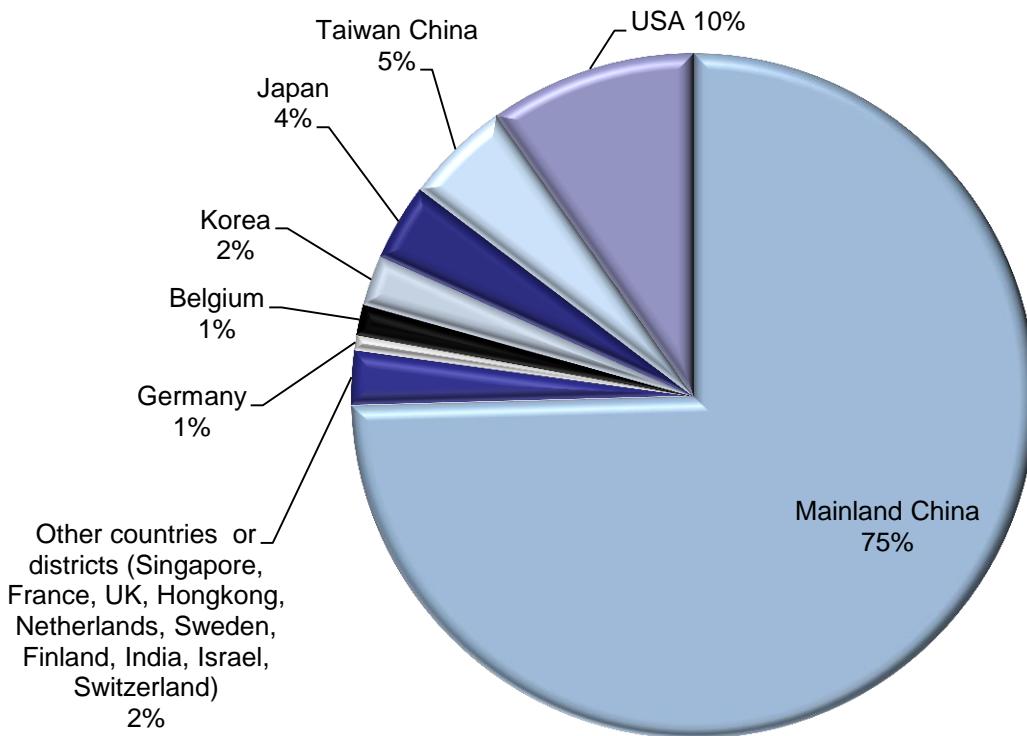
- 70% attendees from industry
- Chip makers like HLMC, HHGrace, Intel, IBM, SMIC, TSMC, UMC, AMT, YMTC, Global Foundries, Samsung, Hynix, JCET, ASE, Huatian and etc. joined the conference
- Design and software companies like Huawei, ZTE, Qualcomm, Lattice, Synopsys, Mentor joined the conference

# Attendee's Job Titles



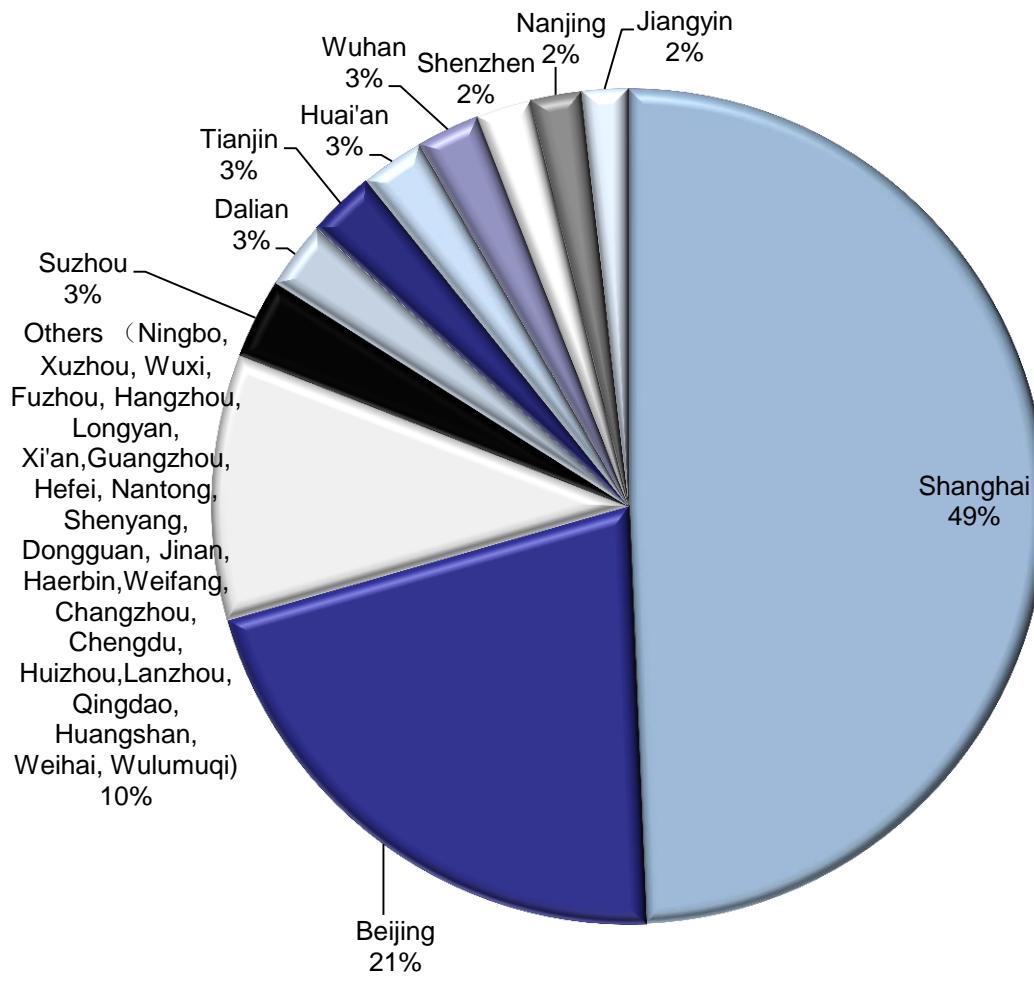
- 27% of our attendees were directors or above, who were the decision makers in companies.

# Attendee Country Distribution



- Speakers and attendees were from 17 different countries or districts
- More than 200 speakers and attendees are oversea industry leaders or experts

# Local Attendee City Distribution



- Speakers and attendees were from 34 different cities in China

# >240 Anticipating Companies



3M  
3MTS  
ACM  
Advantest  
Air Liquide  
A-kelon (Huizhou) Optronics Ltd  
AMEC  
Anji Microelectronics  
Applied Material  
ASAKA RIKEN CO., LTD.  
ASE  
ASML  
ASML Brion  
ASML-Cymer  
Aufirst Chemicals  
Avantor  
Beihang University  
Beijing Chenjing Electronics  
Beijing Normal University  
Beijing Sevenstar  
Beijing Yandong Microelectronics  
Beneq  
BOE  
Brewer Science  
BritelP  
Brooks Instrument  
Bruckewell Technology  
Cabot Microelectronics  
Canon Inc.  
Carl Zeiss  
Changxin Memory Technology  
D2S  
Dai Nippon Printing Co., Ltd.  
Dalian University of Technology  
Darbond  
Delta Electronics  
Department of Electronic Engineering, Feng Chia University  
DIGITIMES  
Diodes  
Disco

DISPLAYLINK UK  
DK Nanotechnology Inc  
Dow Chemical  
Dow DuPont  
Duke University  
DuPont  
East China Normal University  
Ebara  
Edwards  
Electronic Fluorocarbons  
EpiGaN  
Etown IP  
Financial Times China  
Finisar Corporation  
Foxconn  
Fraunhofer ENAS  
French Institute for Scientific Research(CNRS)  
Fudan University  
Fuzhou University  
G&P Technology  
Georgia Institute of Technology  
Gigaphoton Inc.  
Global Research & Innovative Solutions Co.,Ltd.  
Globalfoundries  
Gredmann Group  
Guangdong University of Technology  
Gwangju Institute of Science and Technology  
Hanyang University  
Harbin Institute of Technology  
Hebei University of Technology  
HEIDENHAIN LIMITED  
Hermes Epitek  
HHGrace  
HiSilicon  
Hitachi High-Technologies Corporation  
HLMC  
Hon Hai Precision Industry Co Ltd  
Hua Hong Wuxi  
Huada Emprean  
Huangshan University

Huatian Technology (Kunshan) Electronics Co.,Ltd  
Huawei  
Huazhong University of Science and Technology  
IBM  
IMEC  
IMECAS  
Institute of Computing Technology, Chinese Academy of Sciences  
Intel  
IRSD Roadmap  
ITRI  
JCET  
Jiangsu Advanced Memory Semiconductor Ltd.  
Jiangsu Normal University  
Jiangsun Advanced Memory Technology  
Johoku Chemical  
JSR Shanghai  
Kanomax FMT Inc  
KANOMAX JAPAN INC  
KCTech  
KLA  
Korea Advanced Institute of Science and Technology  
KU Leuven  
Lam Reearch  
Lanzhou University of Technology  
Lattice Semiconductor Co.  
Leuven Instruments  
Liverpool John Moores University  
Macronix  
Mattson Technology  
Mentor Graphics  
Merck Display Materials(Shanghai) Co., Ltd.  
Middlesex Industries SA  
Minghsin University of Science and Technology(MUST)  
MLI  
MooreElite  
Moses Lake Industries, Inc.  
Nanjing University  
Nanjing University of Posts and Telecommunication  
Nanjing University of Technology  
Nanyang Technological University

# >240 Anticipating Companies



Nata Chemicals  
 National Central University  
 National Chiao Tung University  
 National Taiwan Central University  
 National Taiwan University of Science and Technology  
 National Tsing Hua University  
 Naura  
 NBU  
 NCTU  
 Nikon  
 Ningbo University  
 Nissan Chemical Corporation  
 Novel Crystal Technology  
 NuFlare Technology  
 ONRG  
 Pall Corp.  
 PDF  
 Peking University  
 Pes University  
 Photonics  
 Piotech  
 Plasma-Therm  
 PMS  
 Prismark Partners, LLC  
 Purdue University  
 Qorvo, Inc.  
 QSIL  
 Qualcomm  
 Raintree Technologies  
 S&J Electronics  
 Samsung  
 Sanechips  
 Science China Press  
 SCREEN Semiconductors Solutions Co.,Ltd.  
 Senju Metal Industry Co., Ltd.,  
 Seoul Natioanl University  
 Shandong Shengquan  
 Shanghai IC R&D Center Co., Ltd.  
 Shanghai Jiaotong University  
 Shanghai Kaixi Tech  
 Shanghai Microelectronics Equipment

Shanghai Sunrise  
 Shanghai Tech University  
 Shanghai University  
 Shanghai University of Technology  
 SIEMENS  
 SiEn (Qingdao) Integrated Circuits  
 SIMIT  
 SIMMTECH  
 Singulus Technologies AG  
 SITRI  
 SJ Semiconductor (Jiangyin) Corp.  
 SK HYNIX  
 SKW Associates  
 SMIC  
 SMNC  
 Soochow University  
 South University of Science and Technology  
 SPIL  
 Spirox Technology  
 STATS ChipPAC  
 Sungkyunkwan University  
 Suntific Materials  
 Suzhou IV technology  
 Suzhou Shinhao materials LLC  
 Synopsys  
 Tanjin University of Science & Technology  
 Technical University of Munich  
 TEL  
 TEL FSI  
 TFME  
 Thermo Fisher Scientific  
 Tokyo Electron  
 Tokyo Institute of Technology  
 Tongfu Microelectronics  
 Toshiba Memory Corp.  
 Towerjazz  
 Tsinghua University  
 TSMC  
 UC Los Angeles  
 UC San Diego  
 ULVAC

Unimos  
 University of California, Santa Barbara  
 University of Chinese Academy of Sciences  
 University of Electronic Science and Technology of China  
 University of Massachusetts  
 University of Michigan-Shanghai Jiao Tong University Joint Institute  
 University of Notre Dame  
 University of Twente  
 Uppsala University  
 Versum Materials  
 Viking Global Investors  
 Wolfspeed  
 Wuxi Sky Chip Interconnection Technology Co.,Ltd  
 Xi'an UnilC Semiconductors Co., Ltd.  
 Xinanna Electronics Technology  
 Yangtze Memory Technologies Co.  
 Zhejiang University  
 Zijin Jia Bo Electronics  
 Zing Semiconductor  
 ZTE  
 北京元芯碳基集成电路研究院  
 北京紫光存储科技有限公司  
 东莞记忆存储科技有限公司  
 广东惠尔特纳米科技有限公司  
 国新风险投资管理（深圳）有限公司  
 今井 基勝，水戸工業（株）  
 摩西湖（大连）化学工业有限公司  
 南通至晟微电子技术有限公司  
 上海亨斯迈聚氨酯特种材料  
 上海华丽工程技术有限公司  
 深圳阿科威达  
 威海金鼎机械制造股份有限公司  
 无锡湃泰材料科技有限公司  
 武汉华星光电技术有限公司  
 西安奕斯伟硅片技术有限公司  
 芯思想  
 意发薄膜科技(上海)有限公司  
 元智大學  
 浙江舜宇光学  
 中国电子系统工程第二建设有限公司  
 紫金矿业集团黄金冶炼有限公司

# CSTIC 2020 Chair and Co-chairs



Dr. Steve X. Liang  
Chair  
JCET, China



Dr. Qinghuang Lin  
Executive Co-Chair  
ASML, USA



Dr. Ru Huang  
Co-Chair  
Peking University, China



Dr. Cor Claeys  
Co-Chair  
KU Leuven, Belgium



Dr. Hanming Wu  
Co-Chair  
Etown, China

# CSTIC 2020 Symposia and Chairs



Symposium I: Device Engineering and Memory Technology

Symposium II: Lithography and Patterning

Symposium III: Dry & Wet Etch and Cleaning

Symposium IV: Thin Film, Plating and Process Integration

Symposium V: CMP and Post-Polish Cleaning

Symposium VI: Metrology, Reliability and Testing

Symposium VII: Packaging and Assembly

Symposium VIII: MEMS, Sensors and Emerging Semiconductor Technologies

Symposium IX: Design and Automation of Circuits and Systems

Dr.	Ru HUANG	Symp-I, Chair	Peking University, China
Dr.	Kafai LAI	Symp-II, Chair	IBM, USA
Dr.	Ying ZHANG	Symp-III, Chair	Naura, USA
Dr.	Zhen GUO	Symp-IV, Chair	Intel, USA
Dr.	Xinping QU	Symp-V, Chair	Fudan University, China
Dr.	Steve LIANG	Symp-VI, Chair	JCET, China
Dr.	Peilin SONG	Symp-VII, Chair	IBM, USA
Dr.	Qinghuang LIN	Symp-VIII, Chair	ASML, USA.
Dr.	Wenjian YU	Symp-IX, Chair	Tsinghua University, China

# CSTIC 2020 Plan



- CSTIC 2020 will be held on Mar 15-16, 2020 in Shanghai, in conjunction with SEMICON China
- CSTIC 2020 call for papers and manuscript deadlines
  - Call for paper online: Jun. 30, 2019
  - Abstract deadline: Sep. 30, 2019
  - Acceptance notification: Nov. 15, 2019
  - Manuscript deadline: Dec. 26, 2019

Thank you  
See you at CSTIC 2020

**CONNECT**

